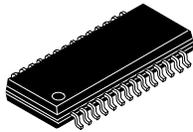


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

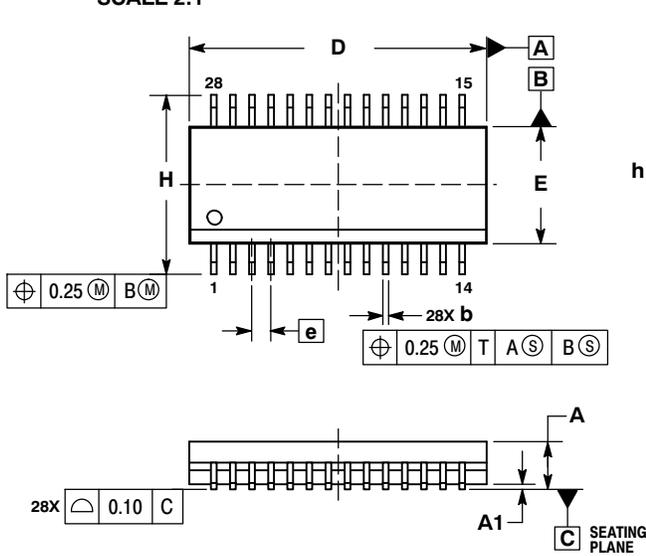
ON Semiconductor®



QSOP28 NB
CASE 492AA-01
ISSUE O

DATE 27 MAR 2008

SCALE 2:1

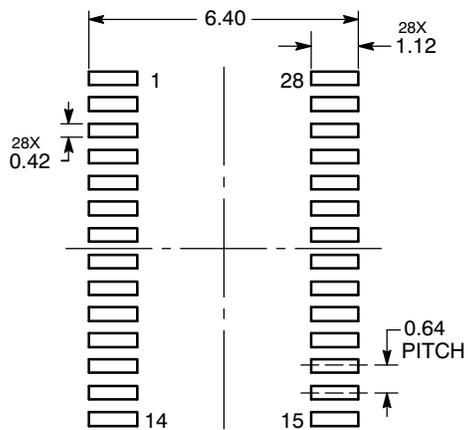


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS OR FLASH. END FLASH SHALL NOT EXCEED 0.25 PER SIDE.

MILLIMETERS		
DIM	MAX	MIN
A	1.35	1.75
A1	0.10	0.25
b	0.20	0.30
C	0.19	0.25
D	9.80	10.00
E	3.80	4.00
e	0.635 BSC	
H	5.79	6.20
h	0.22	0.50
L	0.40	1.27
M	0°	8°

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QSOP28 NB	PAGE 1 OF 2

